

In the claims

Please cancel claim 20 and amend claim 19 as follows:

Marked Up Copy of Amended Claims

19. (Amended three times) A method of assembling (a multi-chip device)
comprising:

providing [fabricating] an interposer having a first surface and a second surface;
populating the second surface with a plurality of conductive pads;
coupling a solder ball to each of selected ones of the plurality of conductive pads;
coupling at least one semiconductor die and at least one passive device to the first
surface, wherein the at least one passive device is selected from a group
comprising resistors, capacitors, and inductors;
testing said at least one semiconductor die; and
coupling said interposer to a substrate with the solder balls after said testing if
said at least one semiconductor die passes said testing.

Clean Copy of All Claims After Amendment

19. (Amended three times) A method of assembling a multi-chip device
comprising:

providing an interposer having a first surface and a second surface;
populating the second surface with a plurality of conductive pads;
coupling a solder ball to each of selected ones of the plurality of conductive pads;
coupling at least one semiconductor die and at least one passive device to the first

surface, wherein the at least one passive device is selected from a group comprising resistors, capacitors, and inductors;

testing said at least one semiconductor die; and

C | coupling said interposer to a substrate with the solder balls after said testing if said at least one semiconductor die passes said testing.

20. (Cancelled)

21. (Amended once) The method of claim 19 wherein fabricating comprises fabricating the interposer with organic material.

22. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises a C4 process.

23. (Amended twice) The method of claim 19 further comprising not coupling said interposer to the substrate if said at least one semiconductor die does not pass said testing.

24. (temporarily removed from consideration) (Amended once) The method of claim 19 further comprising coupling a single chip carrier to the substrate.

25. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises coupling memory chips to the interposer.

26. (Amended once) The method of claim 19, further comprising:
creating a plurality of contacts on the substrate; and
electrically connecting said selected ones of the plurality of conductive pads to the plurality of contacts.